# MMJT350T1G, SMMJT350T1G

# **Bipolar Power Transistors** PNP Silicon

Bipolar power transistors are designed for use in line-operated applications such as low power, line-operated series pass and switching regulators requiring PNP capability.

#### Features

• High Collector-Emitter Sustaining Voltage -

 $V_{CEO(sus)} = 300 \text{ Vdc} @ I_C$ = 1.0 mAdc

• Excellent DC Current Gain -

$$h_{FE} = 30-240 @ I_C$$
  
= 50 mAdc

- Epoxy Meets UL 94 V-0 @ 0.125 in
- ESD Ratings:
  - Human Body Model, 3B; > 8000 V
  - Machine Model, C; > 400 V
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*



## **ON Semiconductor®**

http://onsemi.com

0.5 AMPERE POWER TRANSISTOR PNP SILICON 300 VOLTS, 2.75 WATTS



CASE 318E STYLE 1



#### MARKING DIAGRAM



= Assembly Location

= Year = Work Week

A Y

W

- = Pb-Free Package
- T350 = Device Code

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

| Device      | Package              | Shipping <sup>†</sup> |
|-------------|----------------------|-----------------------|
| MMJT350T1G  | SOT-223<br>(Pb-Free) | 1,000 / Tape & Reel   |
| SMMJT350T1G | SOT-223<br>(Pb-Free) | 1,000 / Tape & Reel   |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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# MMJT350T1G, SMMJT350T1G

# **MAXIMUM RATINGS** (T<sub>C</sub> = $25^{\circ}$ C unless otherwise noted)

| Rating  | Symbol                            | Value                      | Unit                 |
|---|-----------------------------------|----------------------------|----------------------|
| Collector-Emitter Voltage   | V <sub>CEO</sub>                  | 300                        | Vdc                  |
| Collector-Base Voltage  | V <sub>CB</sub>                   | 300                        | Vdc                  |
| Emitter-Base Voltage  | $V_{\text{EB}}$                   | 5.0                        | Vdc                  |
| Collector Current<br>Continuous<br>Peak   | Ι <sub>C</sub>                    | 0.5<br>0.75                | Adc                  |
| Total Power Dissipation<br>@ $T_C = 25^{\circ}C$<br>Derate above 25°C<br>Total P <sub>D</sub> @ $T_A = 25^{\circ}C$ mounted on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material<br>Total P <sub>D</sub> @ $T_A = 25^{\circ}C$ mounted on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material | P <sub>D</sub>                    | 2.75<br>22<br>1.40<br>0.65 | W<br>mW/°C<br>W<br>W |
| Operating and Storage Junction Temperature Range  | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150                | °C                   |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## THERMAL CHARACTERISTICS

| Characteristic   | Symbol   | Мах             | Unit |
|--|--|-----------------|------|
| Thermal Resistance<br>Junction-to-Case<br>Junction-to-Ambient on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material<br>Junction-to-Ambient on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material | R <sub>θJC</sub><br>R <sub>θJA</sub><br>R <sub>θJA</sub> | 45<br>85<br>190 | °C/W |
| Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds  | TL   | 260             | °C   |

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

| Characteristic  | Symbol                 | Min | Max | Unit |
|---|------------------------|-----|-----|------|
| OFF CHARACTERISTICS   |                        |     | •   |      |
| Collector-Emitter Sustaining Voltage<br>(I <sub>C</sub> = 1.0 mAdc, I <sub>B</sub> = 0 Adc) | V <sub>CEO(SUS</sub> ) | 300 | _   | Vdc  |
| Collector-Base Current<br>( $V_{CB}$ = Rated $V_{CBO}$ , $V_{EB}$ = 0)                      | I <sub>CBO</sub>       | _   | 100 | nAdc |
| Emitter Cut-off Current<br>(V <sub>BE</sub> = 5.0 Vdc)                                      | I <sub>EBO</sub>       | _   | 100 | nAdc |
| ON CHARACTERISTICS  |                        |     | •   | •    |
| DC Current Gain   | bee                    |     |     |      |

| DC Current Gain                                       | h <sub>FE</sub> |    |     | - |
|---|-----------------|----|-----|---|
| (I <sub>C</sub> = 50 mAdc, V <sub>CE</sub> = 10 Vdc)  |                 | 30 | 240 |   |
| (I <sub>C</sub> = 100 mAdc, V <sub>CE</sub> = 10 Vdc) |                 | 20 | -   |   |

## MMJT350T1G, SMMJT350T1G



There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 3 is based on  $T_{J(pk)} = 150^{\circ}$ C;  $T_{C}$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}$ C. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.



Figure 5. Power Derating

#### PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04

ISSUE N





NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: INCH.

STYLE 1: PIN 1. BASE

2. COLLECTOR 3. EMITTER 4. COLLECTOR

|     | MILLIMETERS |      |      | INCHES |       |       |  |
|-----|-------------|------|------|--------|-------|-------|--|
| DIM | MIN         | NOM  | MAX  | MIN    | NOM   | MAX   |  |
| Α   | 1.50        | 1.63 | 1.75 | 0.060  | 0.064 | 0.068 |  |
| A1  | 0.02        | 0.06 | 0.10 | 0.001  | 0.002 | 0.004 |  |
| b   | 0.60        | 0.75 | 0.89 | 0.024  | 0.030 | 0.035 |  |
| b1  | 2.90        | 3.06 | 3.20 | 0.115  | 0.121 | 0.126 |  |
| c   | 0.24        | 0.29 | 0.35 | 0.009  | 0.012 | 0.014 |  |
| D   | 6.30        | 6.50 | 6.70 | 0.249  | 0.256 | 0.263 |  |
| Е   | 3.30        | 3.50 | 3.70 | 0.130  | 0.138 | 0.145 |  |
| e   | 2.20        | 2.30 | 2.40 | 0.087  | 0.091 | 0.094 |  |
| e1  | 0.85        | 0.94 | 1.05 | 0.033  | 0.037 | 0.041 |  |
| Г   | 0.20        |      |      | 0.008  |       |       |  |
| L1  | 1.50        | 1.75 | 2.00 | 0.060  | 0.069 | 0.078 |  |
| HE  | 6.70        | 7.00 | 7.30 | 0.264  | 0.276 | 0.287 |  |
| θ   | 0°          | -    | 10°  | 0°     | -     | 10°   |  |

**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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